

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jin Yao</td> <td>10/12/2009</td> </tr> <tr> <td>Xuezhe Zheng</td> <td>10/15/2009</td> </tr> <tr> <td>Ashok V. Krishnamoorthy</td> <td>10/12/2009</td> </tr> <tr> <td>John E. Cunningham</td> <td>10/12/2009</td> </tr> </tbody> </table>		Name	Execution Date	Jin Yao	10/12/2009	Xuezhe Zheng	10/15/2009	Ashok V. Krishnamoorthy	10/12/2009	John E. Cunningham	10/12/2009
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RECEIVING PARTY DATA											
Name:	SUN MICROSYSTEMS, INC.										
Street Address:	4150 Network Circle										
City:	Santa Clara										
State/Country:	CALIFORNIA										
Postal Code:	95054										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12581709</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12581709						
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CORRESPONDENCE DATA											
Fax Number:	(530)759-1665										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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Correspondent Name:	Edward J. Grundler										
Address Line 1:	Park, Vaughan & Fleming, LLP										
Address Line 2:	2820 Fifth Street										
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ATTORNEY DOCKET NUMBER:	SUN10-0036										
NAME OF SUBMITTER:	Edward J. Grundler, Reg. No. 47,615										
Total Attachments: 2											

OP \$40.00 12581709

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**PATENT
 REEL: 023559 FRAME: 0585**

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CORPORATE ASSIGNMENT

WHEREAS, the undersigned,

Jin Yao	10150 Wateridge Circle #129, San Diego, CA 92121
Xuezhe Zheng	12442 Dormouse Road, San Diego, CA 92129
Ashok V. Krishnamoorthy	16132 Cayenne Creek Road, San Diego, CA 92127
John E. Cunningham	12283 Carmel Vista Road, Apt. 116, San Diego, CA 92130

hereinafter termed "Inventor(s)", have invented certain new and useful improvements in

THREE-DIMENSIONAL MACRO-CHIP INCLUDING OPTICAL INTERCONNECTS

and have executed a declaration or oath for an application for a United States patent disclosing and identifying the invention:

___ On the ___ day of _____, 20___;

Or

X Said application having Application Number 12/581,709 and filed on 19 October 2009; and

WHEREAS, SUN MICROSYSTEMS, INC. a corporation of the State of Delaware, having a place of business at 4150 Network Circle, Santa Clara, CA 95054, (hereinafter termed "Assignee"), is desirous of acquiring the entire right, title and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered jointly or severally by said Inventor(s) (all collectively hereinafter termed "said invention"), and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter termed "patents") thereon granted in the United States and foreign countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Inventor(s) to have been received in full from said Assignee:

1. Said Inventor(s) do hereby sell, assign, transfer and convey unto said Assignee the entire right, title and interest (a) in and to said application and said invention; (b) in and to all rights to apply for foreign patents on said invention pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all applications filed and any and all patents granted on said invention in the United States or any foreign country, including each and every application filed and each and every patent granted on any application which is a divisional, substitution, continuation, or continuation-in-part of any of said applications; and (d) in and to each and every reissue or extensions of any of said patents.

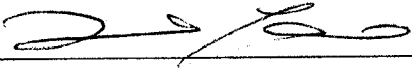
2. Said Inventor(s) hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and foreign countries. Such cooperation by said Inventor(s) shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (d) for filing and prosecuting applications for reissuance of any said patents; (e) for interference or other priority proceedings involving said invention; and (f) for legal proceedings involving said invention and any applications therefor and any patents granted thereon, including without limitation reissues and

reissues and reexaminations, opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventor(s) in providing such cooperation shall be paid for by said Assignee.

3. The terms and covenants of this assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventor(s), their respective heirs, legal representatives and assigns.

4. Said Inventor(s) hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

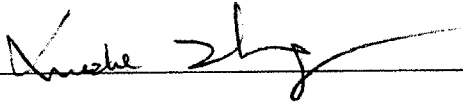
IN WITNESS WHEREOF, said Inventor(s) have executed and delivered this instrument to said Assignee as of the dates written below.



10/12/09

Jin Yao

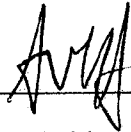
Date



10/15/09

Xuezhe Zheng

Date



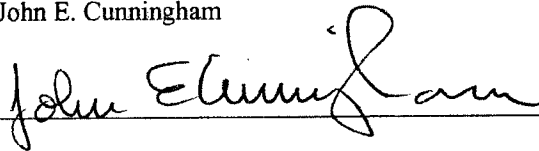
10/12/2009

Ashok V. Krishnamoorthy

Date

John E. Cunningham

Date



10/12/09

Date